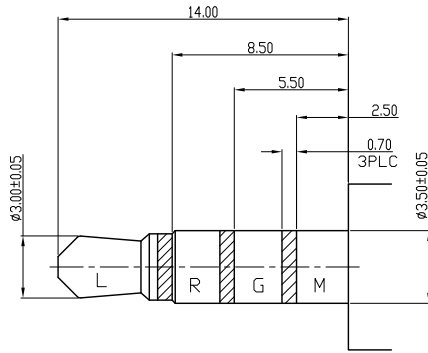
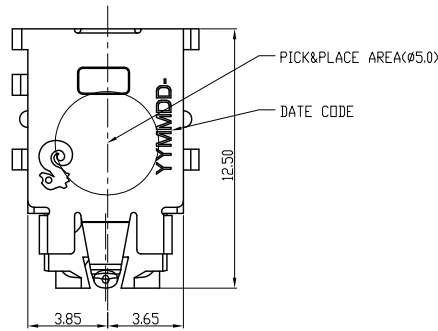


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T140213-1B	Dengfeng	2014.08.09

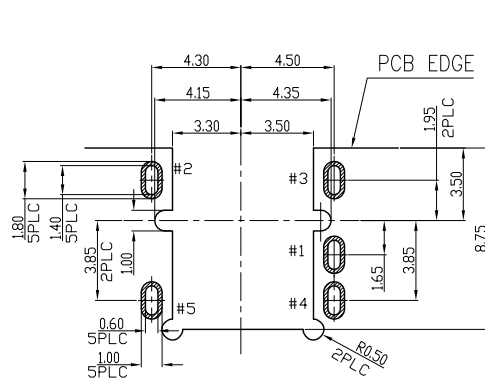
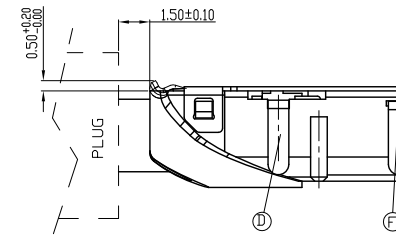
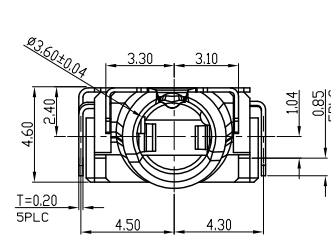
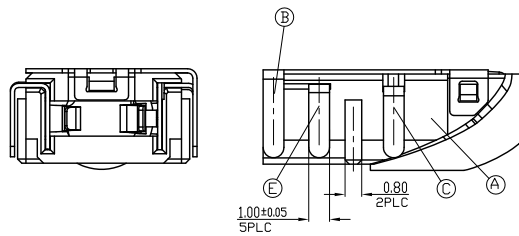


RECOMMENDED PLUG  
4-POLE(±0.05)

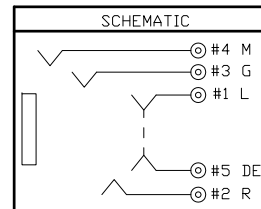
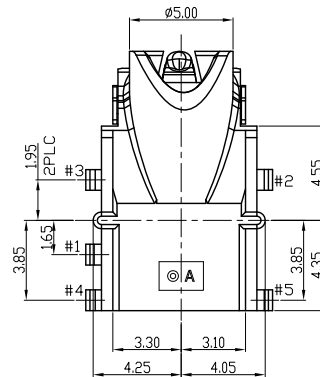


SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
- CONTACT RESISTANCE: 50mΩ MAX.
- INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
- UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
- LIFE TEST: 10,000 CYCLES MIN.
- INSERTION FORCE: 0.3 - 3Kg.
- WITHDRAWAL FORCE: 0.3 - 3Kg.
- AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
- PACKING : TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:



RECOMMENDED PCB LAYOUT(TOP VIEW)  
(TOLERANCE: ±0.05)



F	TIP-B	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA;
E	TIP-A	1	SUS304-1/2H 0.2t	GOLD FLASH ON SOLDER TAIL AREA;
D	RING-A	1	PHOSPHOR BRONZE 0.2t	ALL OVER 50u" NICKET PLATING.
C	RING-B	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA;
B	EARTH	1	PHOSPHOR BRONZE 0.2t	MATTE TIN 120u" SOLDER TAIL AREA;
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	ALL OVER 50u" NICKET PLATING.
				Ni 50u" Min.
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS:	ANGLES:	TITLE	Ø3.50 AUDIO JACK	
X :±0.5	X :±2°	DWN	Dengfeng	PART NO. 2SJ3059-047111F
X.X :±0.3	X.X :±1°	CHKD	Bruce	SCALE:4:1 UNIT: mm
X.XX :±0.2		APVD	Lussen	SIZE: A3 SHEET:1 OF 1 REV: A
CUSTOMER COPY				